

Bonding Source Hot Plates

The microelectronics and RF/Microwave assemblers' choice for pre-tacking epoxy film, epoxy curing, SMD reflow, rework, and wire bonding base heat.

BS-4-6

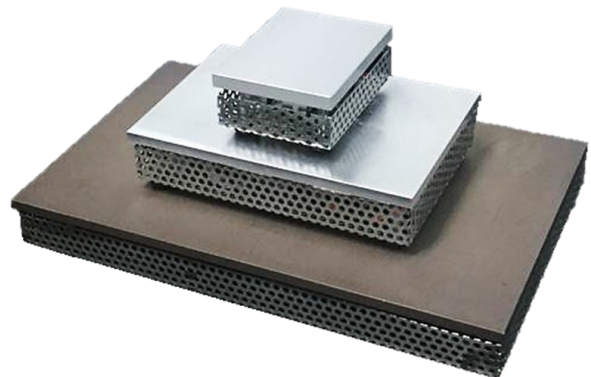


Hot Plate System Features

- Mid-size surface area is perfect for small projects
- Low-profile (1.4" Ht.) hot plate conveniently fits beneath microscopes and wire bond stages
- Modular design: plates can be used interchangeably with Bonding Source digital PID controllers and cable assemblies
- Hot plates are matched in height to 1.4" and available in the following sizes: 10.5"x6.5", 6"x4", and 3"x2.5"
- Digital controller ensures process consistency
- Rapid heating and recovery

Technical Specifications

Overall Dimensions	
• Length	6 in
• Width	4 in
• Height	1.4 in
Heated Area	6in x 4in
Weight	1.2 lbs
Max. Temperature	300 °C
Plate Material	Aluminum (Anodized)
Power Req.	120VAC 60Hz
Thermocouple Cable Length	3 ft
Power Cord Length	6 ft



bonding source

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